ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and	mposition De 5. IPC, Bannockl Pan-American co	claration ourn, Illinois. A opyright conver	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarati he declaration e	on of the substa ncompasses all	nces within the m lower level mater	nanufacturer	listed item. Note h the manufactur	: if the item is an a rer has engineering	ssembly with low responsibility.	
15,0_01	IPC Web Site for Information on IPC-1752 Standard								ous Materials	rials and Mfg Information			
upplier Information													
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2025-07-02			
Contact Name Title -			Fitle - Contact			Phone - Contact*			E	Email - Contact*			
Product-Env-Stewards Pro			Product Enviro Compliance			NA			F	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title			Fitle - Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Pr			Product Enviro Compliance			NA			F	Product-Env-Stewards@onsemi.com			
Requester Item Number			er Mfr Item Name			Effective Date	Version	Manufacturin	ng Site	Weight*	UOM	Unit Type	
	1N54061	1N5406RLG REC		REC AXIAL 3A 600V STD TR		2025-07-02		CNP	CNP		mg	Each	
Ianufacturing Proccess Infor	mation					•	-						
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal Base		Alloy J-STD-020 MSL Ratir		L Rating	Peak Process Body Temperature Max Time		ne at Peak Te	eak Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		seconds 3				
omments													
or more information regarding mate	rial composition	please refer to	page 3										

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.67	mg	Supplier	Silicon (Si)	7440-21-3		6.2331	mg
			В	Nickel (Ni)	7440-02-0		0.0767	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.3602	mg
Die Attach Solder	46.69	mg	Supplier	Silver (Ag)	7440-22-4		1.1673	mg
			А	Lead (Pb)	7439-92-1	7a	43.1882	mg
			Supplier	Tin (Sn)	7440-31-5		2.3345	mg
Lead Frame	731.48	mg	Supplier	Copper (Cu)	7440-50-8		731.48	mg
Mold Compound-Black	543.33	mg		Metal Hydroxide	proprietary data		27.1665	mg
			Supplier	Carbon Black (C)	1333-86-4		5.4333	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		407.4975	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		54.333	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		48.8997	mg
Plating	6.45	mg	Supplier	Tin (Sn)	7440-31-5		6.45	mg